SMT-II
“LOW STATIC”
BOARD CLEANER

teknek

An ITW Company

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SMT-II by Teknek creates a new benchmark in SMT board cleaning. With Low Static Cleaning and Low Applied Pressure SMT-II creates the perfect method for removing contamination before solder paste print. Industry demands for increased traceability and integration have been addressed, SMT-II comes with IPC Hermes as standard.

SPECIFICATION

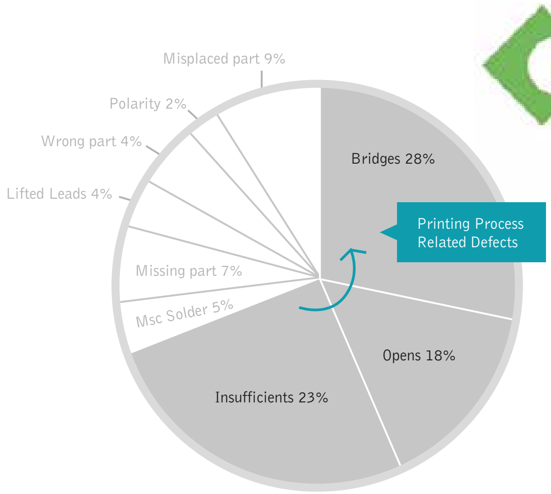
CLEANING WIDTHS	40 - 400mm / 40 - 600mm
OPERATING MODES	SINGLE SIDE or BY-PASS DOUBLE SIDE or BY-PASS
ROLLER TYPES AVAILABLE	NT™ - UTF - Nanocleen™
ADHESIVE AVAILABLE	AREP or AREF
PROCESSING SPEED	1-40 m/min
PASS LINE HEIGHT	900 ± 50mm
MAINS POWER	85 - 265Vac
AIR SUPPLY	5-7 bar ‘OIL FREE AIR’

PRODUCT COMPLIANCE

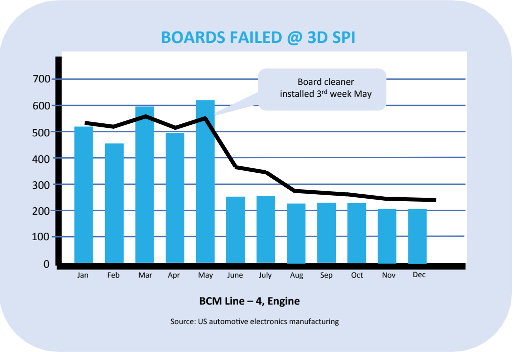
MACHINE	ANSI / ESD s6.1 - 2014 & IEC 61340-5-1 2016
ALL ROLLERS	ISO 6122 CLASS A
NT™ / NANOCLEEN™	ANSI / ESD s20.20 - 2014
ALL ADHESIVES	FINAT

SMT DATA

KOH YOUNG TECHNOLOGY



70%
Approx.


BOARDS FAILED @ 3D SPI

BCM Line – 4, Engine

Source: US automotive electronics manufacturing

FEATURES

BENEFITS

1 nt new technology + 2 teknek eco AREP + 3 Ground Pathways

Low Static Cleaning

Every part of SMT-II has been designed to clean boards within a low static environment. This is achieved through careful design along with patented elastomer and adhesive technology

① NT™ Rollers ② Low Static Adhesive ③ Pathways

IPC-HERMES-9852

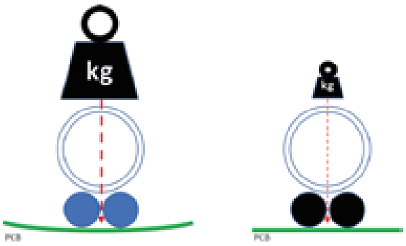
SMEMA

Network

Communication between equipment within the SMT process has never been more important, not only will the SMT-II fully integrate into the process but will also come as standard with IPC-Hermes-9852 or SMEMA capability.

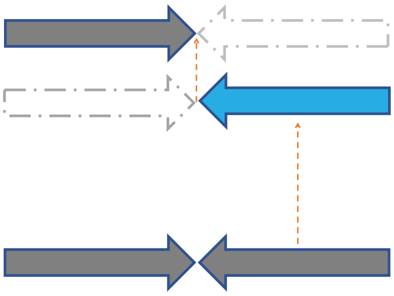
Interface

With a new simple to use graphics user interface, SMT-II is easy to set up and run.



Low Applied Pressure

As technology drives the need for thinner and more complex boards, they can become more fragile. Applied pressure at any point in the assembly process may cause damage. SMT-II boasts the lowest applied pressure of any cleaner bringing high efficiency cleaning with no damage



Follow-Me

An option on the new SMT-II is "Follow-Me". If your SMT process is not being controlled by Hermes, this independent auto width change system continually monitors the moving rail on the machine before or after the SMT-II. During board change overs this feature removes the need for the operator to be involved increasing process up-time.

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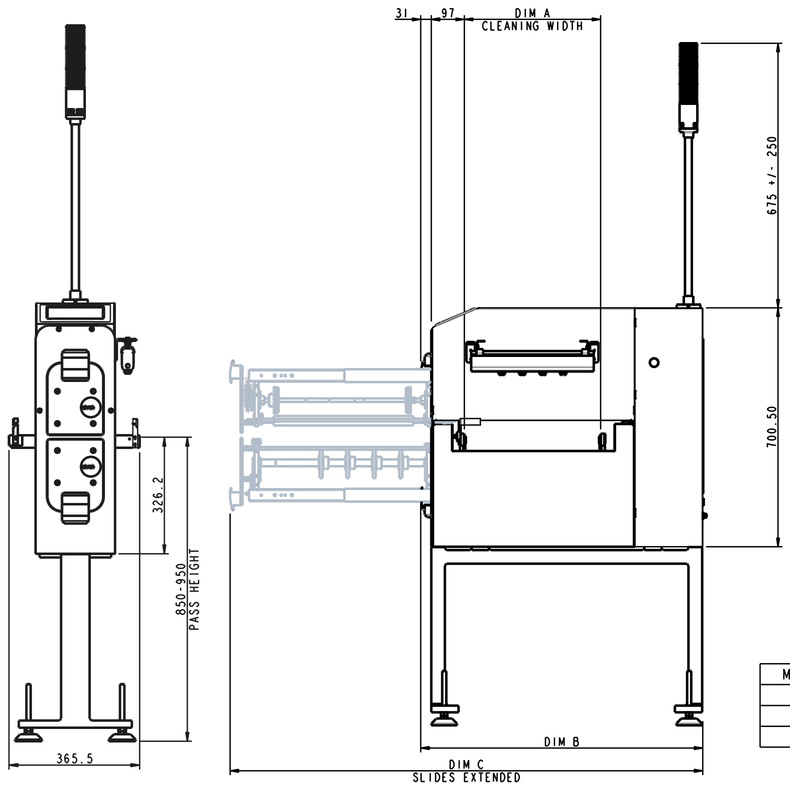
TECHNICAL SPECIFICATION



MACHINE WIDTH	CLEANING WIDTH	OVERALL WIDTH	SLIDES EXTENDED
	DIM A	DIM B	DIM C
SMT-II - 400	400	828	1388
SMT-II - 600	622	1078	1878

CAPABILITY

BOARD PROCESSING			
SINGLE SIDE CLEANING	Min - Max Length Min - Max Width Min - Max Thickness	50mm - N/A 40mm - 400mm 0.6mm - 3.2mm	50mm - N/A 40mm - 600mm 0.6mm - 3.2mm
BY-PASS NO CLEANING	Min - Max Length Min - Max Width Min - Max Thickness	50mm - N/A 40mm - 400mm 0.6mm - 3.2mm	50mm - N/A 40mm - 600mm 0.6mm - 3.2mm
DOUBLE SIDE CLEANING	Min - Max Length Min - Max Width Min - Max Thickness	98mm - N/A 40mm - 400mm 0.6mm - 3.2mm	98mm - N/A 40mm - 600mm 0.6mm - 3.2mm
BY-PASS NO CLEANING	Min - Max Length Min - Max Width Min - Max Thickness	120mm - N/A 40mm - 400mm 0.6mm - 3.2mm	120mm - N/A 40mm - 600mm 0.6mm - 3.2mm

MADE IN UK

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